

DATA SHEET

Product Name Chip Resistors Array

Part Name 2F01/4F01/2C02/4C02/4C03/2D02/2D03/4D02/4D03/4DP3/16P8 Series File No. SMD-SP-024

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1. <u>Scope</u>

- 1.1 This datasheet is the characteristics of chip resistors array manufactured by UNI-ROYAL.
- 1.2 High density, more than 1 resistors in one small case
- 1.3 Improvement of placement efficiency
- 1.4 Tape/Reel packaging is suitable for automatic placement machine
- 1.5 Superior solderability
- 1.6 Application: Master board, CD&DVD Rom, Hard Disk, RAM

2. Part No. System

Part No. includes 14 codes shown as below:

2.1 1st~4th codes: Part name.E.g.: 2D02,4D02,2D03,4D03,4DP3,16P8,2C02, 4C02, 4C03,2F01,4F01.

2.2 $5^{\text{th}} \sim 6^{\text{th}}$ codes: Power rating.

E.g.: W=Normal Size	"1~G" = "1~16"			
Wattage	1/10	1/16	1/20	
Normal Size	WA	WG	WM	

If power rating is equal or lower than 1 watt, 5th code would be "W" and 6th code would be a number or letter.

E.g.: WA=1/10W W4=1/4W

- 2.3 7^{th} code: Tolerance. E.g.: D=±0.5% F=±1% G=±2% J=±5% K=±10%
- 2.4 8th~11th codes: Resistance Value.
- 2.4.1 If value belongs to standard value of E-24 series, the 8^{th} code is zero, $9^{th} \sim 10^{th}$ codes are the significant figures of resistance value, and the 11^{th} code is the power of ten.
- 2.4.2 If value belongs to standard value of E-96 series, the $8^{th} \sim 10^{th}$ codes are the significant figures of resistance value, and the 11^{th} code is the power of ten.
- 2.4.311th codes listed as following:

2.5.3 14th code: Special features.

E = Environmental Protection, Lead Free, or Standard type.

3. Ordering Procedure

(Example: 4C02 1/16W $\pm 5\%$ 100 Ω T/R-10000)





Chip Resistors Array



4. Marking

4.1 Normal for 2D02 & 2C02 & 4C02 size, no marking on the body, 0 Ω resistors is no marking too.



4.2 ±5% Tolerance of 4D02, 2D03, 4D03, 4DP3,4C03 and 16P8 size: the first two digits are significant figures of resistance and the third denotes number of zeros following .



4.3 ±1%Tolerance of 2D03,4D02, 4D03, 4DP3,4C03 and 16P8 size: first three digits are significant figures of resistance and the fourth denotes number of zeros following







	2D03	4D02,4D
	0	
	4C03	16P8
for 2E01	4E01 sizes no marking on the body 0.0	resistors is no r





4.5 Normal for 2F01, 4F01 sizes, no marking on the body.0 Ω resistors is no marking too



2F01

4F01





5. Dimension

5.1 Equivalent Circuit Diagram:



5.2 Dimensions in mm:



H	Flat Terminal
2F01	4F01

Туре	Dimensions (mm)									
турс	L	W	Т	A1	A2	В	Р	G		
2D02(0402*2)	1.00 ± 0.10	1.00 ± 0.10	0.35±0.10	0.33±0.10	/	0.15 ± 0.05	0.65 ± 0.05	0.25±0.10		
4D02(0402*4)	2.00±0.10	1.00 ± 0.10	0.45 ± 0.10	0.40 ± 0.05	0.30±0.05	0.20±0.15	0.50±0.05	0.30±0.15		
2D03(0603*2)	1.60 ± 0.15	1.60±0.15	0.50 ± 0.10	0.60 ± 0.15	/	0.30±0.10	0.80 ± 0.05	0.25±0.10		
4D03/4DP3(0603*4)	3.20±0.20	1.60±0.20	0.50 ± 0.10	0.65 ± 0.15	0.50±0.15	0.30±0.15	0.80±0.10	0.30±0.15		
16P8	4.00±0.20	1.60±0.15	0.45±0.10	0.45 ± 0.05	0.30±0.05	0.30±0.15	0.50 ± 0.05	0.40±0.15		
2C02(0402*2)	1.00 ± 0.10	1.00 ± 0.10	0.35±0.10	/	/	0.15±0.10	/	0.30±0.10		
4C02(0402*4)	2.00±0.10	1.00 ± 0.10	0.45±0.10	/	/	0.15±0.10	/	0.30±0.10		
4C03(0603*4)	3.20±0.20	1.60±0.20	0.60±0.10	/	/	0.30±0.20	/	0.40±0.10		
2F01(0201*2)	0.80 ± 0.10	0.60 ± 0.10	0.35±0.10	0.30±0.10	/	0.15±0.10	0.50±0.05	0.15±0.10		
4F01(0201*4)	1.40±0.10	0.60±0.10	0.35±0.10	0.20±0.10	/	0.15±0.10	0.40±0.05	0.15±0.10		





6. <u>Resistance Range</u>

Туре	Rated power	Max Working Voltage	Max Overload Voltage	Dielectric Withstanding Voltage	Resistance Range ±5%±1%	Temperature Coefficient PPM/°C	Operating Temperature	Resistance Value of Jumper	Rated Current of Jumper	
2D02	1/16W	50V	100V	100V	10Ω~1MΩ	±200				
4D02	1/16W	50V	100V	100V	10Ω~1MΩ	±200				
2D03	1/16W	50V	100V	100V	10Ω~1MΩ	±200				
4002	1/1 CW	501/	7 100V 300V	2001/	10, 110	≥10Ω:±200		<50mΩ	1A	
4D03	1/16W	50V		300 V	1Ω~1ΜΩ	$< 10\Omega:\pm 400$	-55℃~+155℃			
4002	1/10337	501/	10017	2001/	1Ω~1MΩ	≥10Ω:±200				
4DP3	1/10W	50V	100V	300V		$< 10\Omega: \pm 400$				
1.000	1/1/1	501/	10017	2001/	2001/	1Ω~1MΩ	≥10Ω:±200			
16P8	1/16W	50V	100V	100V 300V		$< 10\Omega: \pm 400$				
2C02	1/16W	50V	100V	100V	10Ω~1ΜΩ	±200				
4C02	1/16W	50V	100V	100V	10Ω~1ΜΩ	±200				
4002	1/10337	501/	10017	2001/	10, 11(0	≥10Ω:±200				
4C03	1/10W	50V	100V	300V	1Ω~1MΩ	$< 10\Omega: \pm 400$				
2F01	1/20W	12.5V	25V	/	10Ω~1MΩ	±200	55°0 125°0	-500	1.4	
4F01	1/20W	12.5V	25V	/	10Ω~1MΩ	±200	-55℃~+125℃	<50mΩ	1A	

7. <u>Soldering pad size recommended</u>







Trme	Dimension(mm)										
Туре	Α	В	B1	B2	W	С	P1	D			
2D02	0.5±0.1	0.33±0.1	/	/	2.0±0.1	0.34±0.1	/	1.0±0.1			
4D02	0.5±0.1	0.3±0.1	0.28 ± 0.1	0.28±0.1	2.0±0.1	0.22±0.1	/	1.82±0.1			
2D03	0.8±0.1	0.45 ± 0.05	/	/	2.6±0.2	0.35±0.05	0.8 ± 0.05	/			
4D03	1.0±0.1	0.4±0.1	0.4±0.1	0.4±0.1	2.6±0.1	0.4±0.1	/	2.8±0.1			
4DP3	1.0±0.1	0.4±0.1	0.4±0.1	0.4±0.1	2.6±0.1	0.4±0.1	/	2.8±0.1			
16P8	1.0±0.1	0.3±0.1	0.3±0.1	/	2.3±0.1	0.2±0.1	0.5±0.1	/			
2C02	0.5±0.1	0.3±0.1	/	/	2.0±0.1	0.2±0.1	/	0.8±0.1			
4C02	0.5±0.1	0.3±0.1	0.3±0.1	0.3±0.1	2.0±0.1	0.2±0.1	/	1.8±0.1			
4C03	1.0±0.1	0.4±0.1	0.4±0.1	0.4±0.1	2.6±0.1	0.4±0.1	/	2.8±0.1			
2F01	0.3±0.1	0.3±0.05	/	/	0.9±0.2	0.2±0.05	0.5±0.05	/			
4F01	0.3±0.1	0.2±0.05	/	/	0.9±0.2	0.2±0.05	0.45 ± 0.05	/			





8. Derating Curve

Resistors shall have a power rating based on continuous load operation at an ambient temperature from -55 $^{\circ}$ C to 70 $^{\circ}$ C. For temperature in excess of 70 $^{\circ}$ C, the load shall be derate as shown in figure 1



8.1 Voltage rating:

Resistors shall have a rated direct-current (DC) continuous working

Voltage or an approximate sine-wave root-mean-square (RMS) alternating-current (AC) continuous working voltage at commercial-line frequency and waveform corresponding to the power rating, as determined from the following formula:

 $RCWV = \sqrt{P \times R}$

Where: RCWV commercial-line frequency and waveform (Volt.)

P = power rating (VATT.)

R = nominal resistance (OHM)

The overload voltage is 2.5 times RCWV or Max. Overload voltage whichever is less.

In no case shall the rated DC or RMS AC continuous working voltage be greater than the applicable maximum value.

9. Structure



- 1: High purity alumina substrate
- 2: Protective covering
- 3: Resistive covering
- 4: Termination (inner) Ag/Pd
- 5: Termination (between) Ni plating
- 6: Termination (outer) Sn plating

10. <u>Performance Specification</u>

Characteristic	Limits	Test Methods (GB/T5729&JIS-C-5201&IEC60115-1)
Temperature Coefficient	Reference 6.	4.8 Natural resistance changes per temp. Degree centigrade $\frac{R_2 \cdot R_1}{R_1(t_2 \cdot t_1)} \times 10^6 (PPM/^{\circ}C)$ R_1: Resistance Value at room temperature (t_1); R_2: Resistance at test temperature (t_2) t_1: +25^{\circ}C or specified room temperature t_2: Test temperature (-55^{\circ}C or 125^{\circ}C)
*Short-time overload	±(2.0%+0.1Ω) 2F01: 1%:±1.0%+0.05Ω 5%:±2.0%+0.05Ω	4.13 Permanent resistance change after the application of 2.5 times RCWV for 5 seconds.
	* <50mΩ	Apply max overload current for 0Ω





Terminal bending $\pm (1.0\% \pm 0.05\Omega)$ 4.33 Twist of test board: $Y/x = 3/90 mm$ for 60Seconds* Dielectric withstanding voltageNo evidence of flashover mechanical damage, arcing or insulation breaks down.4.7 Resistors shall be clamped in the troug block and shall be tested at ac potential re the given list of each product type for 60- 260°L5°C and hold it for 10±1 seconds.*Soldering heatResistance change rate is: $\pm (1.0\% \pm 0.05\Omega)$ 4.18 Dip the resistor into a solder bath has $260°L5°C$ and hold it for 10±1 seconds.*SolderabilityCoverage must be over 95%.4.17 The area covered with a new, smooth continuous surface free from concentrated of solder:245±3°C; Dwell time in solder: 2 $245±3°C$; Dwell time in solder: 2Rapid change of temperature $\pm (1.0\% \pm 0.05\Omega)$ $2F01: 1\% : \pm (2.0\% + 0.05\Omega)$ $2F01: 1\% : \pm (2.0\% + 0.1\Omega)$ $5\% : \pm (3.0\% \pm 0.1\Omega)$ 7.9 Resistance change after 1,000 hours (1 "OFF") at RCWV in a humidity chamber and 90 to 95% relative humidity.*Load life in humidity $\pm (3.0\% \pm 0.1\Omega)$ $5\% : \pm (3.0\% \pm 0.1\Omega)$ 4.25.1 Permanent resistance change after RCWV with duty cycle 1.5 hours "ON",0 $\pm 2°C$ ambient.*Load life is trange $\pm (3.0\% \pm 0.1\Omega)$ $5\% : \pm (3.0\% \pm 0.1\Omega)$ IEC 60068-2-1 (Aa) Lower limit temperature, for 2H.*High $\pm (3.0\% \pm 0.\Omega)$ $5\% : \pm (3.0\% \pm 0.1\Omega)$ $5\% : \pm (3.0\% \pm 0.1\Omega)$ IEC 60068-2-1 (Aa) Lower limit temperature, for 2H.	red with a direct voltage lectric withstanding				
withstanding voltagedamage, arcing or insulation breaks down.block and shall be tested at ac potential re the given list of each product type for 60- 					
heat $\pm (1.0\% \pm 0.05\Omega)$ $260^{\circ} C \pm 5^{\circ} C$ and hold it for 10 ± 1 seconds.*SolderabilityCoverage must be over 95%. 4.17 The area covered with a new, smooth continuous surface free from concentrated of solder: $245\pm 3^{\circ} C$; Dwell time in solder: 2Rapid change of temperature $\pm (1.0\% \pm 0.05\Omega)$ $2F01: 1\% : \pm 0.5\% \pm 0.05\Omega$ 4.19 30 min at lower limit temperature and temperature $\rightarrow 100$ cycles.*Load life in humidity $\pm (3.0\% \pm 0.1\Omega)$ $2F01: 1\% : \pm (2.0\% \pm 0.1\Omega)$ $2F01: 1\% : \pm (2.0\% \pm 0.1\Omega)$ 7.9 Resistance change after 1,000 hours (1 "OFF") at RCWV in a humidity chamber and 90 to 95% relative humidity.*Load life is humidity $\pm (3.0\% \pm 0.1\Omega)$ $2F01: 1\% : \pm (2.0\% \pm 0.1\Omega)$ $2F01: 1\% : \pm (2.0\% \pm 0.1\Omega)$ $2F01: 1\% : \pm (2.0\% \pm 0.1\Omega)$ $2F01: 1\% : \pm (3.0\% \pm 0.1\Omega)$ $4.25.1$ Permanent resistance change after RCWV with duty cycle 1.5 hours "ON", 0 $\pm 2^{\circ}C$ ambient.*Load life *Load life * *<50mQ	spectively specified in				
*SolderabilityCoverage must be over 95%.continuous surface free from concentrated of solder:245±3°C; Dwell time in solder: 2Rapid change of temperature $\pm (1.0\% \pm 0.05\Omega)$ $2F01: 1\%:\pm 0.5\% + 0.05\Omega$ $5\%:\pm 1.0\% \pm 0.05\Omega$ 4.19 30 min at lower limit temperature and temperature \cdot 100 cycles.*Load life in humidity $\pm (3.0\% \pm 0.1\Omega)$ $2F01: 1\%:\pm (2.0\% + 0.1\Omega)$ $5\%:\pm (3.0\% \pm 0.1\Omega)$ 7.9 Resistance change after 1,000 hours (1 "OFF") at RCWV in a humidity chamber and 90 to 95% relative humidity.*Load life is humidity $\pm (3.0\% \pm 0.1\Omega)$ $5\%:\pm (3.0\% \pm 0.1\Omega)$ 7.9 Resistance change after 1,000 hours (1) "OFF") at RCWV in a humidity chamber and 90 to 95% relative humidity.*Load life $\pm (3.0\% \pm 0.1\Omega)$ $5\%:\pm (3.0\% \pm 0.1\Omega)$ 4.25.1 Permanent resistance change after RCWV with duty cycle 1.5 hours "ON", 0 $\pm 2^{\circ}C$ ambient.*Low Temperature Storage $\pm (3.0\% \pm 0.1\Omega)$ $5\%:\pm (3.0\% \pm 0.1\Omega)$ $5\%:\pm (3.0\% \pm 0.1\Omega)$ IEC 60068-2-1 (Aa) Lower limit temperature, for 2H.*High $\pm (3.0\% \pm 0.1\Omega)$ $5\%:\pm (3.0\% \pm 0.1\Omega)$ IEC 60068-2-1 (Aa) Lower limit temperature, for 2H.	ving a temperature of				
Rapid change of temperature $2F01: 1\%:\pm 0.5\%+0.05\Omega$ $5\%:\pm 1.0\%\pm 0.05\Omega$ 4.19 30 mm at lower limit temperature and temperature $\cdot 100$ cycles. *Load life in humidity $\pm (3.0\%\pm 0.1\Omega)$ $2F01: 1\%:\pm (2.0\%+0.1\Omega)$ $5\%:\pm (3.0\%\pm 0.1\Omega)$ 7.9 Resistance change after 1,000 hours (1 "OFF") at RCWV in a humidity chamber and 90 to 95% relative humidity. *Coad life $\pm (3.0\%\pm 0.1\Omega)$ $5\%:\pm (3.0\%\pm 0.1\Omega)$ Apply to rated current for 0\Omega *Load life $\pm (3.0\%\pm 0.1\Omega)$ $2F01: 1\%:\pm (2.0\%+0.1\Omega)$ $5\%:\pm (3.0\%\pm 0.1\Omega)$ 4.25.1 Permanent resistance change after RCWV with duty cycle 1.5 hours "ON",0 ± 2 "C ambient. *Low Temperature Storage $\pm (3.0\%\pm 0.1\Omega)$ $2F01: 1\%:\pm (2.0\%+0.1\Omega)$ $2F01: 1\%:\pm (2.0\%+0.1\Omega)$ $2F01: 1\%:\pm (2.0\%+0.1\Omega)$ $2F01: 1\%:\pm (2.0\%+0.1\Omega)$ $2F01: 1\%:\pm (2.0\%+0.1\Omega)$ $5\%:\pm (3.0\%\pm 0.1\Omega)$ IEC 60068-2-1 (Aa) Lower limit temperature, for 2H. *High $\pm (3.0\%\pm 0.1\Omega)$ $\pm (3.0\%\pm 0.1\Omega)$ IEC 60068-2-1 (Aa) Lower limit temperature, for 2H.	pinholes. Temperature				
	d 30 min at upper limit				
*Load life $\pm (3.0\% \pm 0.1\Omega)$ 4.25.1 Permanent resistance change after RCWV with duty cycle 1.5 hours "ON",0 *Load life $2F01: 1\%: \pm (2.0\% + 0.1\Omega)$ $\pm 2^{\circ}C$ ambient. *<50mΩ					
*Load life $ \begin{array}{c} 2F01: 1\%: \pm (2.0\%+0.1\Omega) \\ 5\%: \pm (3.0\%\pm0.1\Omega) \\ $					
$ \begin{array}{c} *Low \\ Temperature \\ Storage \end{array} $					
*Low Temperature Storage $ \begin{array}{c} 2F01: 1\%:\pm (2.0\%+0.1\Omega) \\ 5\%:\pm (3.0\%\pm0.1\Omega) \\ * <50m\Omega \\ \end{array} $ IEC 60068-2-1 (Aa) Lower limit temperature, for 2H. $\begin{array}{c} +(3.0\%\pm0.1\Omega) \\ \pm(3.0\%\pm0.1\Omega) \\ \end{array} $	Apply to rated current for 0Ω				
*High $\pm (3.0\% \pm 0.1\Omega)$					
*High					
Inight Temperature Exposure $2F01: 1\%:\pm (2.0\%+0.1\Omega)$ $5\%:\pm (3.0\%\pm0.1\Omega)$ MIL-STD-202 108A Upper limit temperature, for 1000H.					
* <50mΩ					
*Leaching No visible damage J-STD-002 Test D Samples completely immersed for 30 sec	in solder bath at $260^\circ\!\mathrm{C}$				
The resistors of 0Ω only can do the characteristic noted of *					





11. Soldering Condition

- (This is for recommendation, please customer perform adjustment according to actual application)
- 11.1 Recommend Reflow Soldering Profile : (solder : Sn96.5 / Ag3 / Cu0.5)



Profile Feature	Lead (Pb)-Free solder
Preheat:	
Temperature Min (Ts _{min})	150°C
Temperature Max (Ts _{max})	200°C
Time $(Ts_{min} \text{ to } Ts_{max})$ (ts)	60 -120 seconds
Average ramp-up rate:	
(Ts max to Tp)	3° C / second max.
Time maintained above :	
Temperature (T _L)	217°C
Time (t_L)	60-150 seconds
Peak Temperature (Tp)	260°C
Time within $^{+0}_{-5}$ °C of actual peak Temperature (tp) ²	10 seconds
Ramp-down Rate	6°℃/second max.
Time 25 [°] C to Peak Temperature	8minutes max.

Allowed Re-flow times : 2 times

Remark : To avoid discoloration phenomena of chip on terminal electrodes, please use N2 Re-flow furnace .

11.2 Recommend Wave Soldering Profile : (Apply to 0603 and above size)





Chip Resistors Array



12. Packing of Surface Mount Resistors

12.1 Dimension of Paper Taping : (Unit: mm)

Туре	A ±0.2	B ±0.2	C ±0.05	+0.1 ΦD -0	E ±0.1	F ±0.05	G ±0.1	W ±0.2	T ±0.1
2D02/2C02	1.20	1.20	2.00	1.50	1.75	3.50	4.00	8.00	0.45
4D02/4C02	1.20	2.20	2.00	1.50	1.75	3.50	4.00	8.00	0.70
2F01	0.79	1.00	2.00	1.50	1.75	3.50	4.00	8.00	0.50
4F01	0.90	1.70	2.00	1.50	1.75	3.50	4.00	8.00	0.50







Туре	A ±0.2	B ±0.2	C ±0.05	+0.1 ΦD -0	+0.25 ΦD1 -0	E ±0.1	F ±0.05	G ±0.1	W ±0.2	T ±0.1
16P8	1.80	4.30	2.00	1.50	1.00	1.75	5.50	4.00	12.00	0.75

12.3 Dimension of Reel : (Unit: mm)

		А	В	С	D	М	W
Туре	Qty/Reel	± 0.5	± 0.5	± 0.5	± 1.0	± 2.0	± 1.0
2D02	10,000PCS	2.0	13.0	21.0	60.0	178.0	10.0
4D02	10,000PCS	2.0	13.0	21.0	60.0	178.0	10.0
2D03	5,000PCS	2.0	13.0	21.0	60.0	178.0	10.0
4D03	5,000PCS	2.0	13.0	21.0	60.0	178.0	10.0
4DP3	5,000PCS	2.0	13.0	21.0	60.0	178.0	10.0
16P8	4,000PCS	2.0	13.0	21.0	60.0	178.0	13.8
2C02	10,000PCS	2.0	13.0	21.0	60.0	178.0	10.0
4C02	10,000PCS	2.0	13.0	21.0	60.0	178.0	10.0
4C03	5,000PCS	2.0	13.0	21.0	60.0	178.0	10.0
2F01	15,000PCS	2.0	13.0	21.0	60.0	178.0	10.0
4F01	15,000PCS	2.0	13.0	21.0	60.0	178.0	10.0



13. <u>Note</u>

13.1. UNI-ROYAL recommend products store in warehouse with temperature between 15 to 35 °C under humidity between 25 to 75% RH. Even under storage conditions recommended above, solder ability of products will be degraded stored over 1 year old.

- 13.2. Cartons must be placed in correct direction which indicated on carton, otherwise the reel or wire will be deformed.
- 13.3. Storage conditions as below are inappropriate:
 - a. Stored in high electrostatic environment
 - b. Stored in direct sunshine, rain, snow or condensation.

c. Exposed to sea wind or corrosive gases, such as Cl_2 , H_2S , NH_3 , SO_2 , NO_2 , Br etc.

14. Record

Version	Description	Page	Date	Amended by	Checked by
1	First version	1~9	Mar.20, 2018	Haiyan Chen	Nana Chen
2	Modify 2F01,4F01 packing quantity	8	Jun.06, 2018	Haiyan Chen	Nana Chen
3	Modify characteristic	6~7	Feb.18, 2019	Haiyan Chen	Yuhua Xu
4	Modify the High Temperature Exposure conditions	7	July.29, 2019	Haiyan Chen	Yuhua Xu
5	Modify the reflow curve and add the wave soldering curve	8	Apr.29, 2020	Haiyan Chen	Yuhua Xu
6	Modify the temperature coefficient test conditions	6	Oct.26, 2022	Haiyan Chen	Yuhua Xu

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